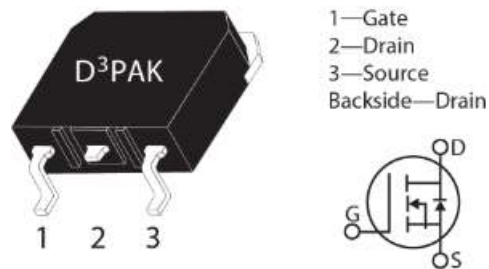


MSC080SMA120S Silicon Carbide N-Channel Power MOSFET

Product Overview

The silicon carbide (SiC) power MOSFET product line from Microsemi increases the performance over silicon MOSFET and silicon IGBT solutions while lowering the total cost of ownership for high-voltage applications. The MSC080SMA120S device is a 1200 V, 80 mΩ SiC MOSFET in a TO-268 (D3PAK) package.



Features

The following are key features of the MSC080SMA120S device:

- Low capacitances and low gate charge
- Fast switching speed due to low internal gate resistance (ESR)
- Stable operation at high junction temperature, $T_{J(max)} = 175\text{ °C}$
- Fast and reliable body diode
- Superior avalanche ruggedness
- RoHS compliant

Benefits

The following are benefits of the MSC080SMA120S device:

- High efficiency to enable lighter, more compact system
- Simple to drive and easy to parallel
- Improved thermal capabilities and lower switching losses
- Eliminates the need for external freewheeling diode
- Lower system cost of ownership

Applications

The MSC080SMA120S device is designed for the following applications:

- PV inverter, converter, and industrial motor drives
- Smart grid transmission and distribution
- Induction heating and welding
- H/EV powertrain and EV charger
- Power supply and distribution

Device Specifications

This section shows the specifications for the MSC080SMA120S device.

Absolute Maximum Ratings

The following table shows the absolute maximum ratings of the MSC080SMA120S device.

Table 1 • Absolute Maximum Ratings

Symbol	Parameter	Ratings	Unit
V _{DSS}	Drain source voltage	1200	V
I _D	Continuous drain current at T _C = 25 °C	35	A
	Continuous drain current at T _C = 100 °C	25	
	Pulsed drain current ¹	87	
V _{GS}	Gate-source voltage	23 to -10	V
P _D	Total power dissipation at T _C = 25 °C	182	W
	Linear derating factor	1.21	W/°C

Note:

1. Repetitive rating: pulse width and case temperature limited by maximum junction temperature.

The following table shows the thermal and mechanical characteristics of the MSC080SMA120S device.

Table 2 • Thermal and Mechanical Characteristics

Symbol	Characteristic	Min	Typ	Max	Unit
R _{θJC}	Junction-to-case thermal resistance		0.55	0.83	°C/W
T _J	Operating junction temperature	-55		175	°C
T _{STG}	Storage temperature	-55		150	
T _L	Soldering temperature for 10 seconds (1.6 mm from case)			260	
Wt	Package weight		0.14		oz
			4.0		g

Electrical Performance

The following table shows the static characteristics of the MSC080SMA120S device. $T_J = 25\text{ }^\circ\text{C}$ unless otherwise specified.

Table 3 • Static Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0\text{ V}$ $I_D = 100\text{ }\mu\text{A}$	1200			V
$R_{DS(on)}$	Drain-source on resistance ¹	$V_{GS} = 20\text{ V}$ $I_D = 15\text{ A}$		80	100	m Ω
$V_{GS(th)}$	Gate-source threshold voltage	$V_{GS} = V_{DS}$ $I_D = 1\text{ mA}$	1.8	2.8		V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Threshold voltage coefficient	$V_{GS} = V_{DS}$ $I_D = 1\text{ mA}$		-4.5		mV/ $^\circ\text{C}$
I_{DSS}	Zero gate voltage drain current	$V_{DS} = 1200\text{ V}$ $T_J = 25\text{ }^\circ\text{C}$ $V_{GS} = 0\text{ V}$			100	μA
		$V_{DS} = 1200\text{ V}$ $T_J = 125\text{ }^\circ\text{C}$ $V_{GS} = 0\text{ V}$			500	
I_{GSS}	Gate-source leakage current	$V_{GS} = 20\text{ V}$			100	nA
		$V_{GS} = -10\text{ V}$			100	

Note:

1. Pulse test: pulse width < 380 μs , duty cycle < 2%.

The following table shows the dynamic characteristics of the MSC080SMA120S device. $T_J = 25\text{ }^\circ\text{C}$ unless otherwise specified.

Table 4 • Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
C_{iss}	Input capacitance	$V_{GS} = 0\text{ V}, V_{DD} = 1000\text{ V}$ $V_{AC} = 25\text{ mV}, f = 1\text{ MHz}$		838		μF
C_{rss}	Reverse transfer capacitance			9		
C_{oss}	Output capacitance			84		
Q_g	Total gate charge	$V_{GS} = -5\text{ V}/20\text{ V}, V_{DD} = 800\text{ V}$ $I_D = 15\text{ A}$		64		nC
Q_{gs}	Gate-source charge			12		

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit	
Q_{gd}	Gate-drain charge			19			
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 800\text{ V}$, $V_{GS} = -5\text{ V}/20\text{ V}$ $I_D = 15\text{ A}$, $R_{G(ext)} = 4\ \Omega^1$ Freewheeling diode = MSC080SMA120S ($V_{GS} = -5\text{ V}$)		5		ns	
t_r	Current rise time			4			
$t_{d(off)}$	Turn-off delay time			21			
t_f	Current fall time			15			
E_{on}	Turn-on switching energy ²				319		μJ
E_{off}	Turn-off switching energy				52		
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 800\text{ V}$, $V_{GS} = -5\text{ V}/20\text{ V}$ $I_D = 15\text{ A}$, $R_{G(ext)} = 4\ \Omega^1$ Freewheeling diode = MSC015SDA120B		4		ns	
t_r	Current rise time			4			
$t_{d(off)}$	Turn-off delay time			24			
t_f	Current fall time			19			
E_{on}	Turn-on switching energy ²				199		μJ
E_{off}	Turn-off switching energy				50		
ESR	Equivalent series resistance	$f = 1\text{ MHz}$, 25 mV, drain short		1.9		Ω	
SCWT	Short circuit withstand time	$V_{DS} = 960\text{ V}$, $V_{GS} = 20\text{ V}$ $T_C = 25\text{ }^\circ\text{C}$		3		μs	
E_{AS}	Avalanche energy, single pulse	$V_{DS} = 150\text{ V}$, $I_D = 15\text{ A}$ $T_C = 25\text{ }^\circ\text{C}$		1000		mJ	

Notes:

1. R_G is total gate resistance excluding internal gate driver impedance.
2. E_{on} includes energy of the freewheeling diode.

The following table shows the body diode characteristics of the MSC080SMA120S device. $T_J = 25\text{ }^\circ\text{C}$ unless otherwise specified.

Table 5 • Body Diode Characteristics

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
V_{SD}	Diode forward voltage	$I_{SD} = 15\text{ A}$, $V_{GS} = 0\text{ V}$		4.0		V
V_{SD}	Diode forward voltage	$I_{SD} = 15\text{ A}$, $V_{GS} = -5\text{ V}$		4.2		V
t_{rr}	Reverse recovery time	$I_{SD} = 15\text{ A}$, $V_{GS} = -5\text{ V}$ $V_{DD} = 800\text{ V}$ $di/dt = -1000\text{ A}/\mu\text{s}$		34		ns
Q_{rr}	Reverse recovery charge			200		nC
I_{RRM}	Reverse recovery current			6.5		A

Typical Performance Curves

This section shows the typical performance curves of the MSC080SMA120S device.

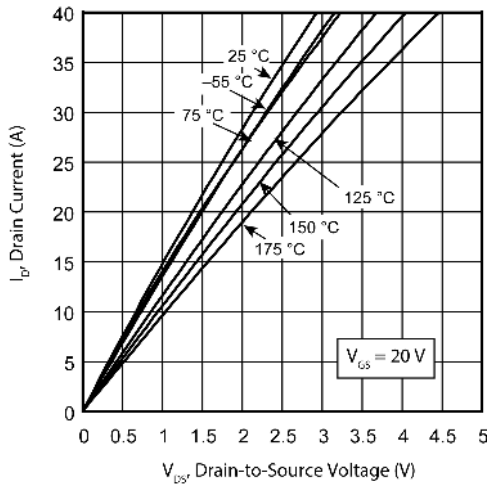


Figure 1 • Drain Current vs. V_{DS}

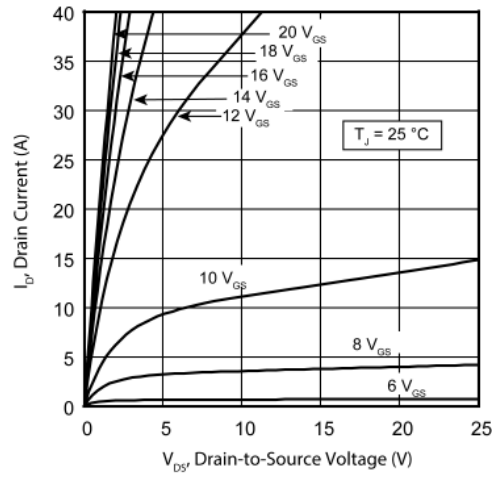


Figure 2 • Drain Current vs. V_{DS}

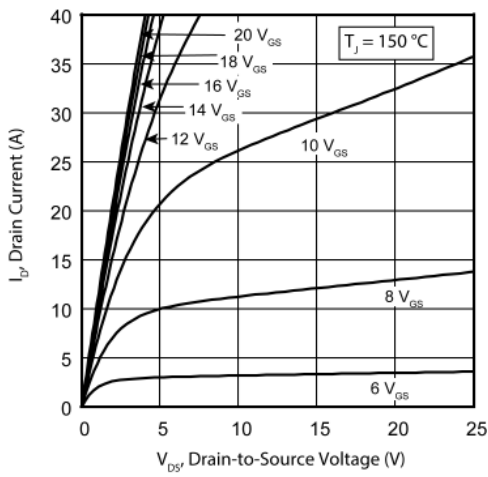


Figure 3 • Drain Current vs. V_{DS}

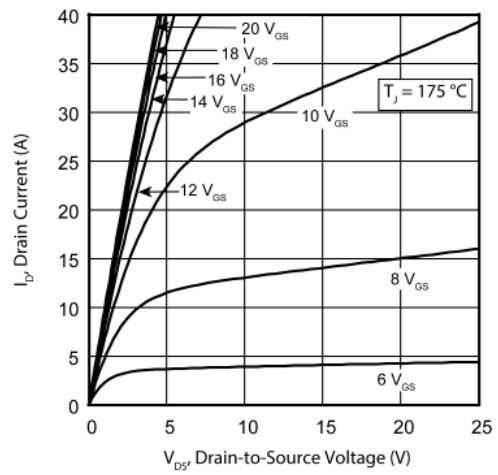


Figure 4 • Drain Current vs. V_{DS}

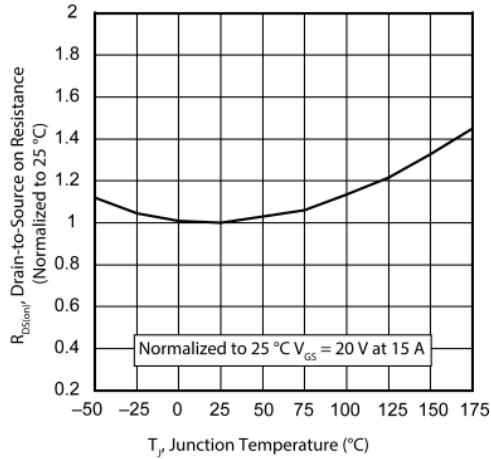


Figure 5 • $R_{DS(on)}$ vs. Junction Temperature

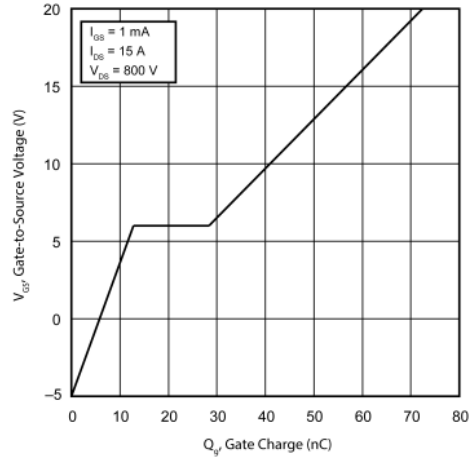


Figure 6 • Gate Charge Characteristics

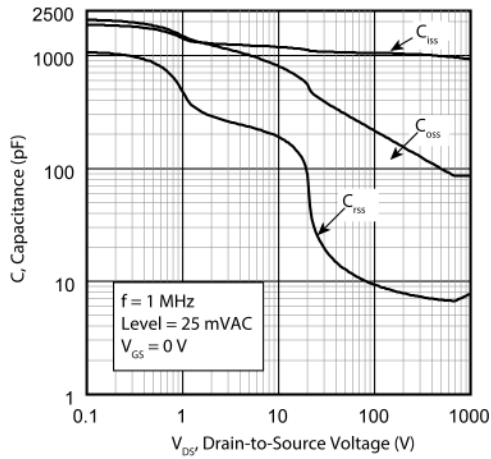


Figure 7 • Capacitance vs. Drain-to-Source Voltage

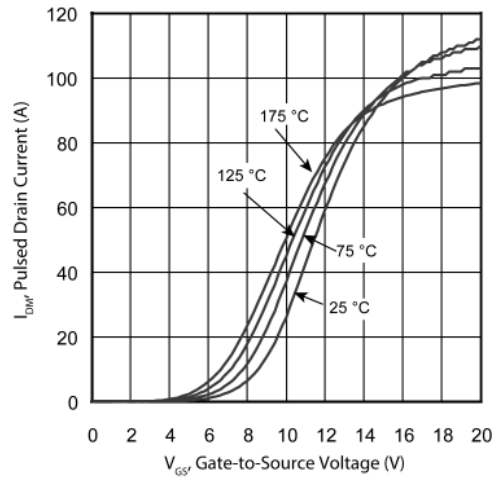


Figure 8 • I_{DM} vs. Gate-to-Source Voltage

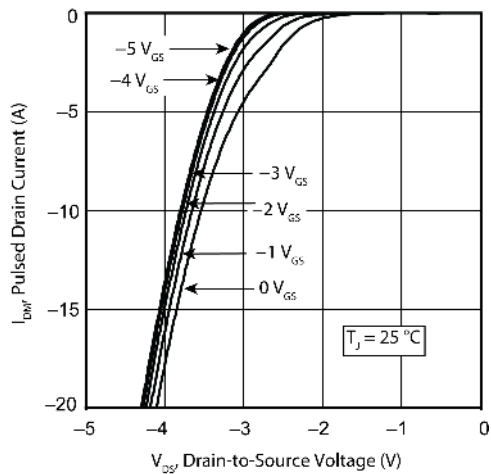


Figure 9 • I_{DM} vs. V_{DS} 3rd Quadrant Conduction

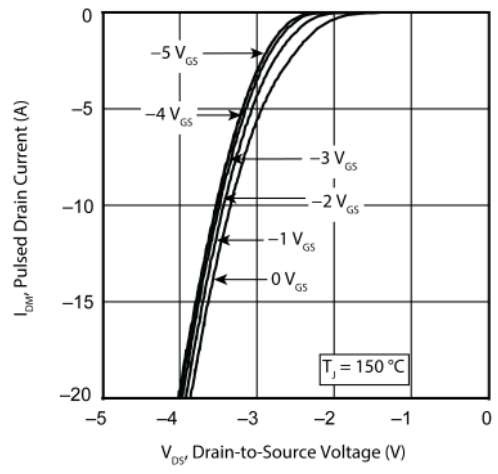


Figure 10 • I_{DM} vs. V_{DS} 3rd Quadrant Conduction

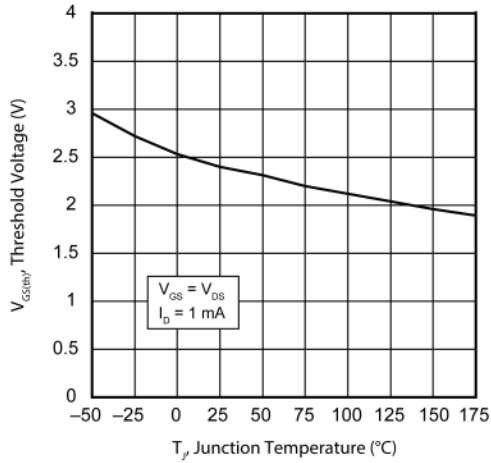


Figure 11 • $V_{GS(th)}$ vs. Junction Temp.

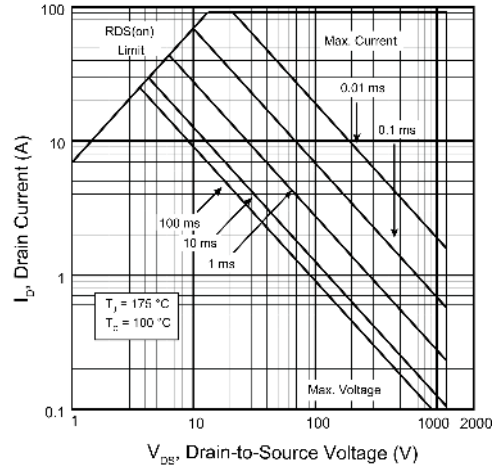


Figure 12 • Forward Safe Operating Area

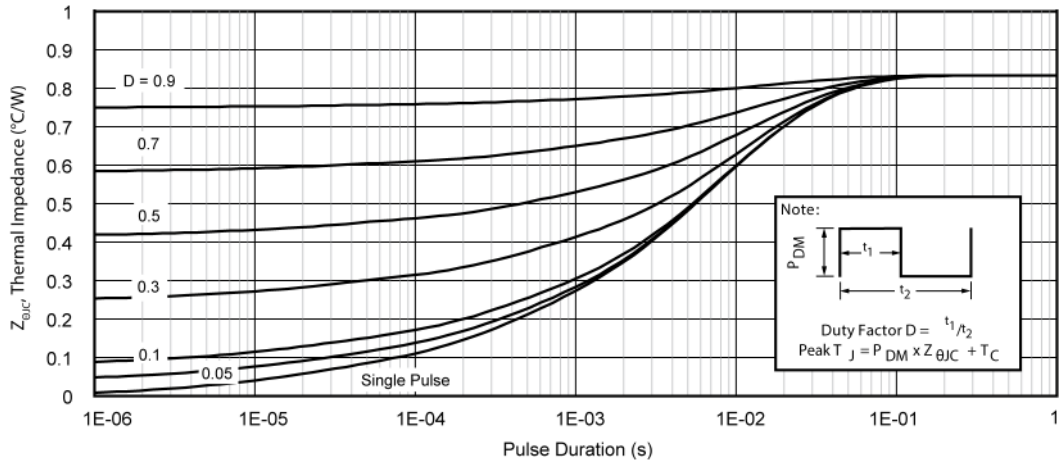


Figure 13 • Maximum Transient Thermal Impedance

Package Specification

This section shows the package specification of the MSC080SMA120S device.

Package Outline Drawing

The following figure illustrates the TO-268 package outline of the MSC080SMA120S device.

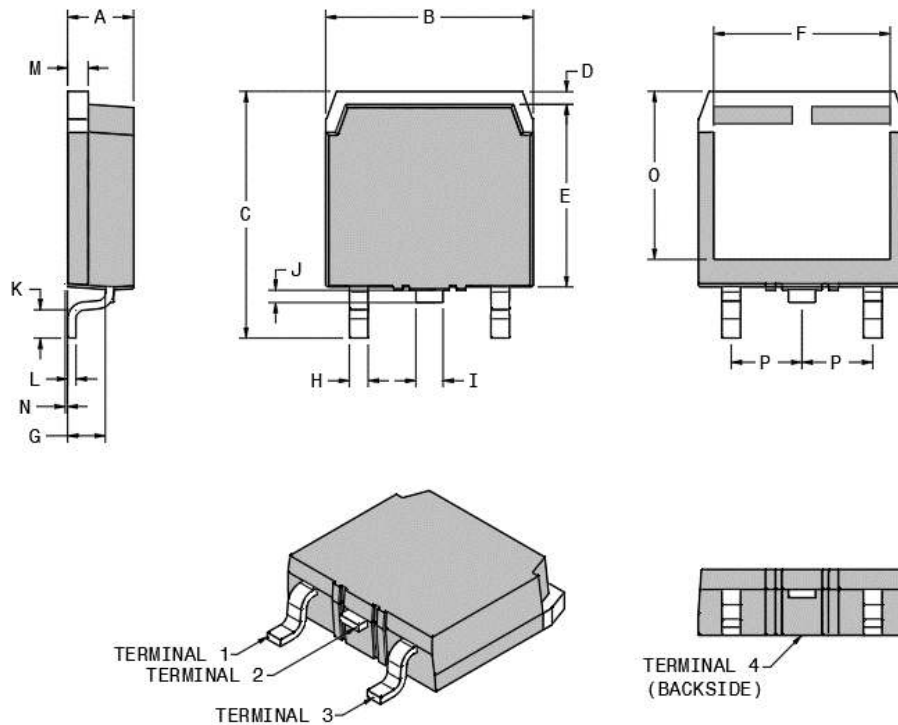


Figure 14 • Package Outline Drawing

The following table shows the TO-268 dimensions and should be used in conjunction with the package outline drawing.

Table 6 • TO-268 Dimensions

Symbol	Min (mm)	Max (mm)	Min (in.)	Max (in.)
A	4.90	5.10	0.193	0.201
B	15.85	16.20	0.624	0.638
C	18.70	19.10	0.736	0.752
D	1.00	1.25	0.039	0.049
E	13.80	14.00	0.543	0.551
F	13.30	13.60	0.524	0.535

Symbol	Min (mm)	Max (mm)	Min (in.)	Max (in.)
G	2.70	2.90	0.106	0.114
H	1.15	1.45	0.045	0.057
I	1.95	2.21	0.077	0.087
J	0.94	1.40	0.037	0.055
K	2.40	2.70	0.094	0.106
L	0.40	0.60	0.016	0.024
M	1.45	1.60	0.057	0.063
N	0.00	0.18	0.000	0.007
O	12.40	12.70	0.488	0.500
P	5.45 BSC (nom.)		0.215 BSC (nom.)	
Terminal 1	Gate			
Terminal 2	Drain			
Terminal 3	Source			
Terminal 4	Drain			

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